

Part Number: APBA3010SURKCGKC-GX



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

Hyper Red
Green

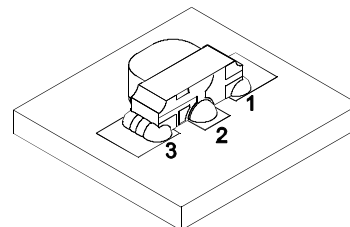
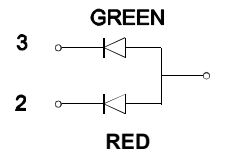
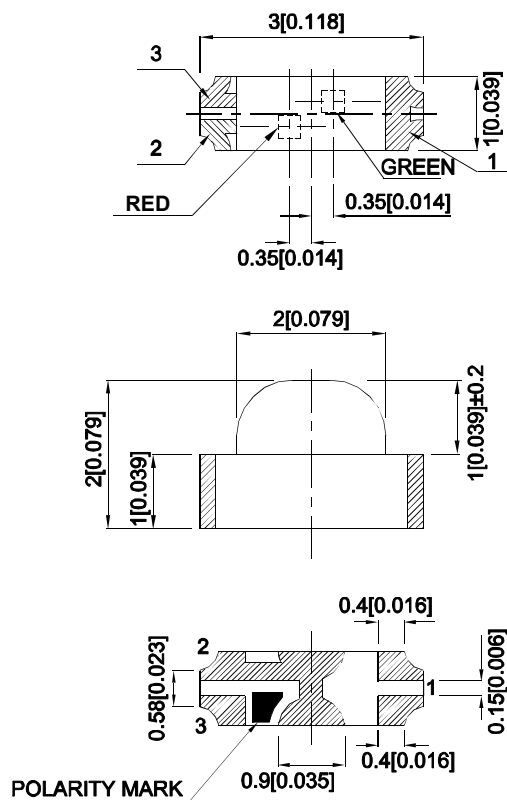
Features

- 3.0x2.0x1.0mm right angle SMD LED, 1.0mm thickness.
- Low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Package : 2000 pcs / reel.
- Moisture sensitivity level : level 3.
- Tinned pads for improved solderability
- RoHS compliant.

Descriptions

- The Hyper Red source color devices are made with Al GaInP on GaAs substrate Light Emitting Diode.
- The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.
- Electrostatic discharge and power surge could damage the LEDs.
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.
- All devices, equipments and machineries must be electrically grounded.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.15(0.006)$ unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.



Selection Guide

Part No.	Emitting Color (Material)	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
APBA3010SURKCGKC-GX	Hyper Red (AlGaInP)	Water Clear	120	300	140°
			*40	*80	
	Green (AlGaInP)		40	70	
			*40	*70	

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ Luminous Flux: +/-15%.
- * Luminous intensity value is traceable to CIE127-2007 standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red Green	645 574		nm	I _F =20mA
λD [1]	Dominant Wavelength	Hyper Red Green	630 570		nm	I _F =20mA
Δλ1/2	Spectral Line Half-width	Hyper Red Green	28 20		nm	I _F =20mA
C	Capacitance	Hyper Red Green	35 15		pF	V _F =0V;f=1MHz
V _F [2]	Forward Voltage	Hyper Red Green	1.95 2.1	2.5 2.5	V	I _F =20mA
I _R	Reverse Current	Hyper Red Green		10 10	μA	V _R = 5V

Notes:

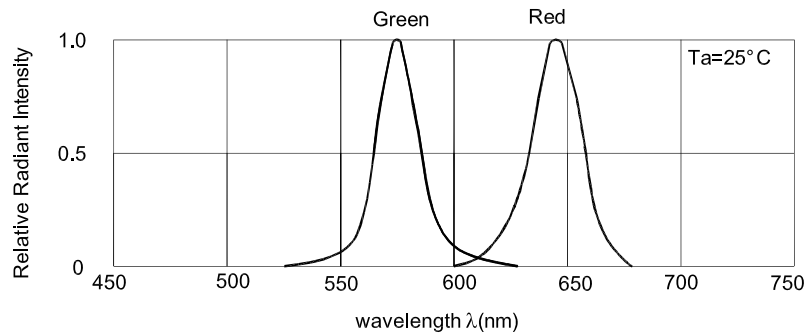
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.
3. Wavelength value is traceable to CIE127-2007 standards.
4. Excess driving current and/or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red	Green	Units
Power dissipation	75	75	mW
DC Forward Current	30	30	mA
Peak Forward Current [1]	185	150	mA
Reverse Voltage	5		V
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

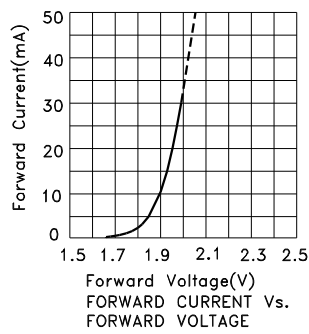
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

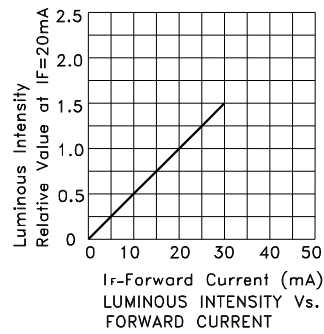


Relative Intensity Vs. Wavelength

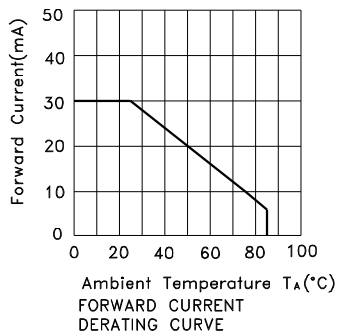
APBA3010SURKCGKC-GX Hyper Red



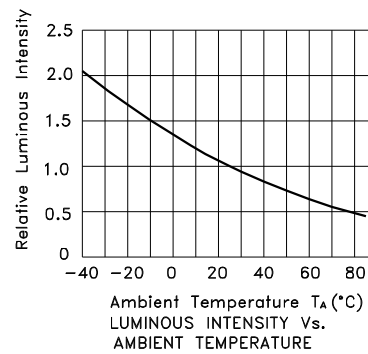
Forward Current(mA)
Forward Voltage(V)
FORWARD CURRENT Vs.
FORWARD VOLTAGE



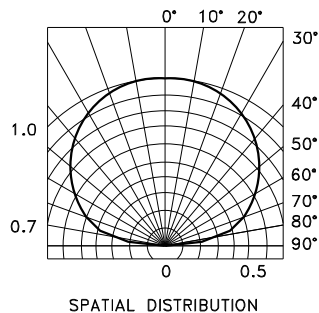
Luminous Intensity
Relative Value at If=20mA
If-Forward Current (mA)
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



Forward Current(mA)
Ambient Temperature Ta(°C)
FORWARD CURRENT
DERATING CURVE

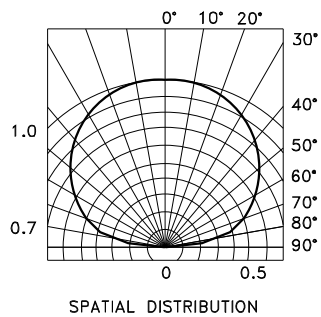
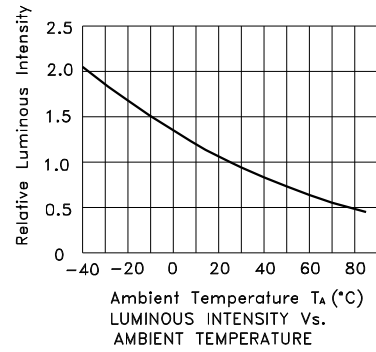
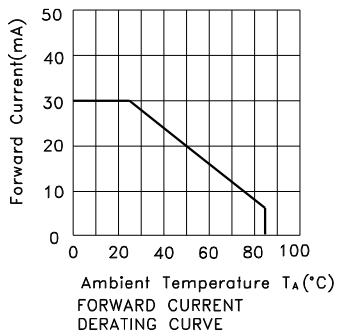
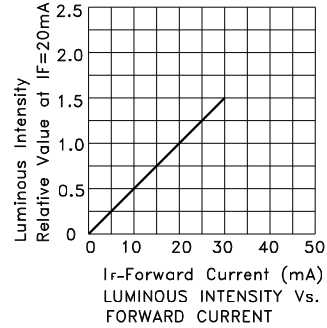
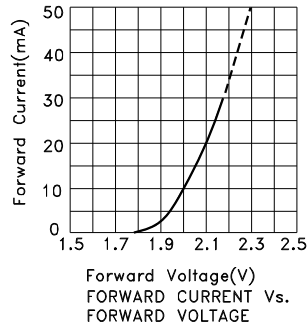


Relative Luminous Intensity
Ambient Temperature Ta(°C)
LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE



SPATIAL DISTRIBUTION

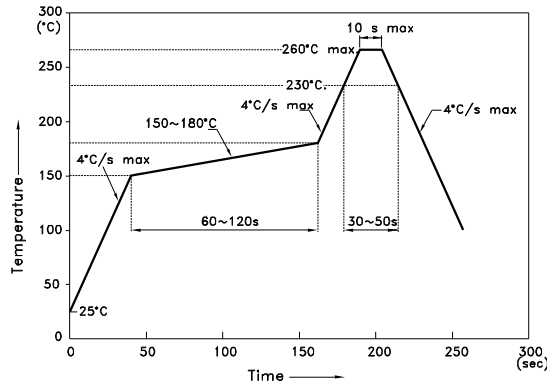
Green



APBA3010SURKCGKC-GX

Reflow soldering is recommended and the soldering profile is shown below.
Other soldering methods are not recommended as they might cause damage to the product.

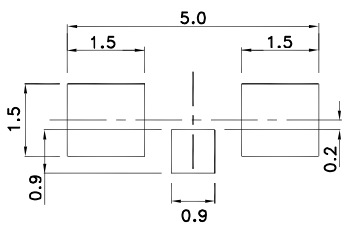
Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

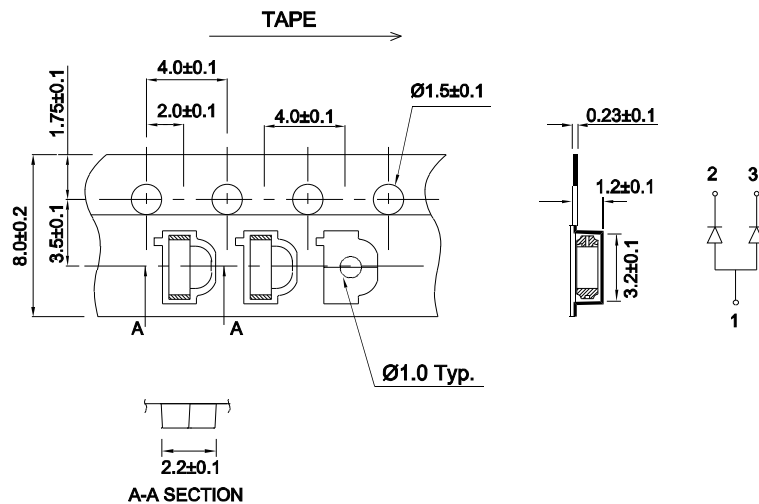
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension

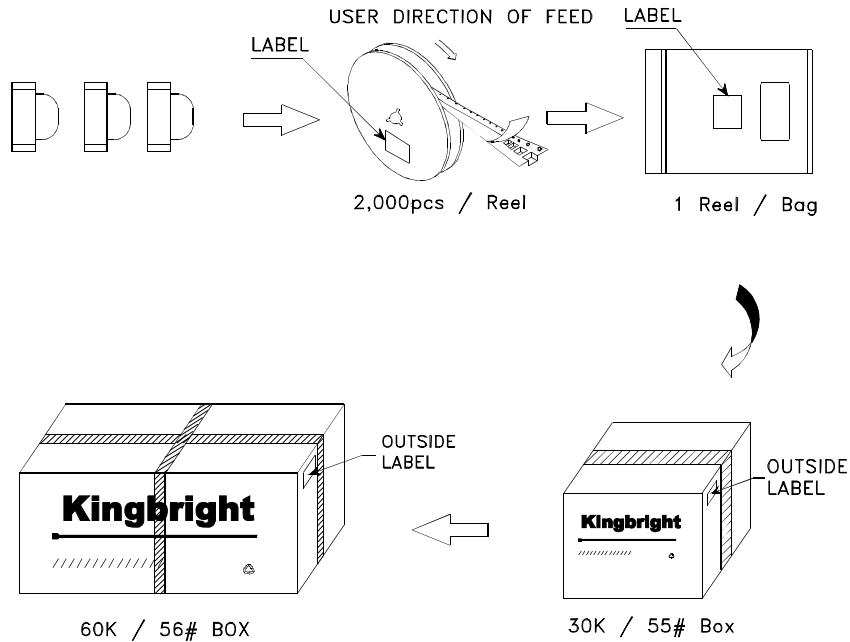



Tape Dimensions (Units : mm)



PACKING & LABEL SPECIFICATIONS

APBA3010SURKCGKC-GX



Kingbright	
P/NO: APBA3010XXX	
QTY: 2,000 pcs	Q.C. Q C XX XX XXXX PASSED
S/N: XXXX	
CODE: XXX	
LOT NO:	
 <small>XXXXXXXXXXXXXXXXXXXX</small>	
RoHS Compliant	

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